

Customer No.: 31561
Application No.: 10/709,990
Docket No.: 11416-US-PA

REMARKS

Present Status of the Application

This is a full and timely response to the outstanding final Office Action mailed on June 6, 2005. The Office Action has rejected claims 1-3, 5-6, 8-9 as being unpatentable over US 4009027 to Naidich et al. (USP 4009027) in view of JP 06081057.

Upon entry of the amendments in this response, claims 1-3, 5-6, 8-9 remaining pending of which claim 1 has been amended. It is believed that no new matter is added by way of these amendments made to the claims or otherwise to the application. Reconsideration and withdrawal of the Examiner's rejection are respectfully requested.

Response to Rejections under 35 U.S.C. 103

Claims 1-3, 6, 8-11 and 13-14 are rejected under 35 U.S.C. 103(a) as being unpatentable over USP 4009027 to Naidich et al. in view of JP 06081057, Applicants respectfully transverse the rejection for at least the reasons set forth below.

The present invention teaches, as recited in independent claim 1, a solder composition, adapted to bond metallic and non-metallic materials, that comprises chromium (Cr) in an amount of 5~20 wt.%; stibium (Sb) in an amount of 11~50 wt.%; a component selected from the group consisting of tin (Sn), zinc (Zn), bismuth (Bi), indium (In) and a mixture thereof; another component selected from the IIIB group in the periodic table or a mixture thereof in an amount of 9~20 wt.%; and an impurity. On the other hand, Naidich teaches an alloy composition for metallization and brazing in general in which very low concentration of stibium (antimony), for example, 0.001 to 10 weight percent is used. A higher Sb content

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improves the wetting behavior between solder and UBM. Further, although the JP patent teaches an incorporation of Ce in a Cu-Fe alloy, the concentration of Ce, which is between 0.005 to 8 wt. %, is also far below the required concentration of a IIIB group component of the instant application.

Accordingly, Applicants respectfully submit that the combination of Naidich with the JP patent still fails to render the present invention unpatentable. Reconsideration and withdrawal of the rejection are respectfully requested.

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CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 1-3, 5-6, and 8-9 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,

Belinda Lee
Belinda Lee

Registration No.: 46,863

Jianq Chyun Intellectual Property Office
7th Floor-1, No. 100
Roosevelt Road, Section 2
Taipei, 100
Taiwan
Tel: 011-886-2-2369-2800
Fax: 011-886-2-2369-7233
Email: belinda@jicpgroup.com.tw
Usa@jicpgroup.com.tw